

REMARKS

The courtesy extended by Examiner Haider during the telephonic discussion on February 26, 2008, is greatly appreciated. During the discussion, a proposed revision to claim 1 to recite a certain level of solder heat resistance was proposed and it was explained that this feature had been previously argued and was now being included in the claims pursuant to the statement by Examiner Haider on page 5 of the Official Action wherein it was noted that this feature was not included in the claims. Examiner Haider indicated that this seemed like an appropriate approach and it was agreed to present an Amendment with this claim revision.

By the present Amendment, the proposed revision to claim 1 discussed with Examiner Haider has been formally presented. It will be noted that on page 25 of the specification, the improved solder heat resistance of the metal laminate is described (and distinguished from high heat resistance). In addition, Table 2 on page 35 sets forth a variety of illustrative metal laminates, all of which have a solder heat resistance of not less than 300°C. It will also be recalled that applicants have previously submitted a Declaration Under 37 C.F.R. §1.132 on February 15, 2007, to show that there is not a direct correlation between tensile strength and solder heat resistance.

Although applicants believe that the former claims of record were patentable over the cited prior art for the reasons which have been previously presented, applicants respectfully submit that the amended claims are clearly patentable. The cited prior art, particularly the combination of Yamaya et al., U.S. Patent No. 4,987,207, Matsuura et al., U.S. Patent No. 5,508,357, and Arai et al., U.S. Patent No. 6,054,509, does not in any way disclose or suggest the specifically defined metal

laminate of the present invention. In particular, the cited prior art does not recognize that the metal laminate comprising a layer of a resin composition obtained by compounding a bismaleimide compound represented by defined formula (1) which recites, *inter alia*, a substitution position on the benzene ring in which X or N has a substitution position of meta to that of another X or N that is bonded to the same benzene ring; a metal foil layer which is a rolled copper foil or an electrolytic copper foil, and one or more polyimide film(s) can provide significant advantageous results, especially the recited level of solder heat resistance.

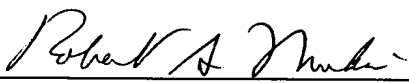
The specific shortcomings of Yamaya et al. and Matsuura et al. have been previously discussed and a further explanation is not needed here. Arai et al. has been solely cited for a teaching of electrolytic copper foil and, even if this further combination is justified, it would also not lead to the invention as defined in the claims now of record. Accordingly, applicants respectfully submit that the presently claimed invention is patentable over the cited prior art and therefore request reconsideration and allowance of the present application.

Should the Examiner have any questions concerning the subject application, the Examiner is invited to contact the undersigned attorney at the number provided below.

Respectfully submitted,

BUCHANAN INGERSOLL & ROONEY PC

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By: 
Robert G. Mukai
Registration No. 28,531

P.O. Box 1404
Alexandria, Virginia 22313-1404
(703) 836-662